

IN THE SPECIFICATION:

Please replace paragraph number [0001] with the following rewritten paragraph:

[0001] This application is a continuation of application Serial No. 10/357,586, filed February 3, 2003, ~~pending now~~ U.S. Patent 6,730,995, issued May 4, 2004, which is a continuation of application Serial No. 10/092,216, filed March 5, 2002, now U.S. Patent 6,538,311, issued March 25, 2003, which is a divisional of application Serial No. 09/879,171, filed June 12, 2001, now U.S. Patent 6,444,501, issued September 3, 2002.

Please replace paragraph number [0037] with the following rewritten paragraph:

[0037] ~~Fig.~~ FIG. 9D is an enlarged perspective view of a cutter die;

Please replace paragraph number [0049] with the following rewritten paragraph:

[0049] For ensuring easy retrieval of semiconductor card 10 from the receiving slot of an apparatus (not shown), a groove 60 may be formed in the card at the noninsertable end 61, preferably on the ~~front~~ face side 20. The groove 60 acts as a finger grip or fingernail grip. The groove 60 is shown as a feature of the second molded plastic casting 28.

Please replace paragraph number [0079] with the following rewritten paragraph:

[0079] As shown in drawing FIG. 12, the second molded plastic casting 28 has rounded junctures 52, 54 of the card peripheral edge 50 with the ~~upper~~ front side 20 and ~~lower~~ back side 22 of the completed semiconductor card 10.